

## **H<sub>2</sub> dilution effect in the Cat-CVD processes of the SiH<sub>4</sub>/NH<sub>3</sub> system**

### **Abstract**

Gas-phase diagnostics in the catalytic chemical vapor deposition processes of the SiH<sub>4</sub>/NH<sub>3</sub>/H<sub>2</sub> system were carried out to examine the effect H<sub>2</sub> dilution. The decomposition efficiency of NH<sub>3</sub> showed a sharp decrease with the introduction of a small amount of SiH<sub>4</sub>, but this decrease was recovered by the addition H<sub>2</sub> when the NH<sub>3</sub> pressure was low. On the other hand, at higher NH<sub>3</sub> pressures, the decomposition efficiency showed a minor dependence on the H<sub>2</sub> partial pressure. The addition of SiH<sub>4</sub> to the NH<sub>3</sub> system decreases the H-atom density by one order of magnitude, but this decrease is also recovered by H<sub>2</sub> addition. H atoms produced from H<sub>2</sub> must re-activate the catalyzer surfaces poisoned by SiH<sub>4</sub> when the NH<sub>3</sub> pressure is low.

### **I. Introduction**

Catalytic chemical vapor deposition [Cat-CVD], Often called hot-wire CVD, is one of the most promising techniques for preparing thin amorphous silicon nitride (SiN<sub>x</sub>) films at low substrate temperatures using SiH<sub>4</sub> and NH<sub>3</sub> as material gases. SiN<sub>x</sub> films thus prepared can be used as gas- and water-resistant coatings for organic and inorganic devices and as interlayer insulating films for microelectronic devices. One of the problems in this technique has been the low decomposition efficiency of NH<sub>3</sub> in the presence of SiH<sub>4</sub>.

In the absence of SiH<sub>4</sub>, NH<sub>3</sub> can be decomposed to NH<sub>3</sub> and H with a decomposition efficiency of more than 50%. However, the decomposition efficiency decreases sharply upon the introduction of a small amount of SiH<sub>4</sub>. This decrease has been attributed to the poisoning of the catalyzer surfaces by SiH<sub>4</sub>. Separating the catalyzers, one to decompose NH<sub>3</sub>, and another to decompose SiH<sub>4</sub> is not easy because the diffusional rate of SiH<sub>4</sub> is large under low pressure conditions, such as those employed in conventional low-pressure CVD processes, and the prevention of catalyzer poisoning is difficult.

Recently, it has been found that the addition of H<sub>2</sub> improves not only the

decomposition efficiency of  $\text{NH}_3$  in the presence of  $\text{SiH}_4$ , but also the  $\text{SiN}_x$  film quality. For example, Malian et al. have shown that the content of N atoms in the films increases significantly with  $\text{H}_2$  dilution for a given  $\text{NH}_3/\text{SiH}_4$  gas flow ratio.  $\text{H}_2$  dilution also causes a reduction in the amount of N-H bonding in  $\text{SiN}_x$  films. Wang et al. have demonstrated that near perfect conformal surface coverage can be obtained on a 100-nm-scale object [6]. In the present work, a systematic study was carried out to determine the catalytic decomposition efficiency of  $\text{NH}_3$  in the  $\text{SiH}_4/\text{NH}_3/\text{H}_2$  system. Such information is essential for optimizing of the deposition conditions to prepare  $\text{SiN}_x$  conformal films. The absolute H-atom densities were also measured under several conditions.